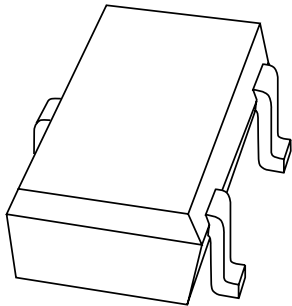


DATA SHEET



PMST2222; PMST2222A NPN switching transistors

Product data sheet
Supersedes data of 1997 Jul 14

1999 Apr 22

NPN switching transistors

PMST2222; PMST2222A

FEATURES

- High current (max. 600 mA)
- Low voltage (max. 40 V).

APPLICATIONS

- High-speed switching and linear amplification.

DESCRIPTION

NPN switching transistor in a SOT323 plastic package.
PNP complement: PMST2907A.

MARKING

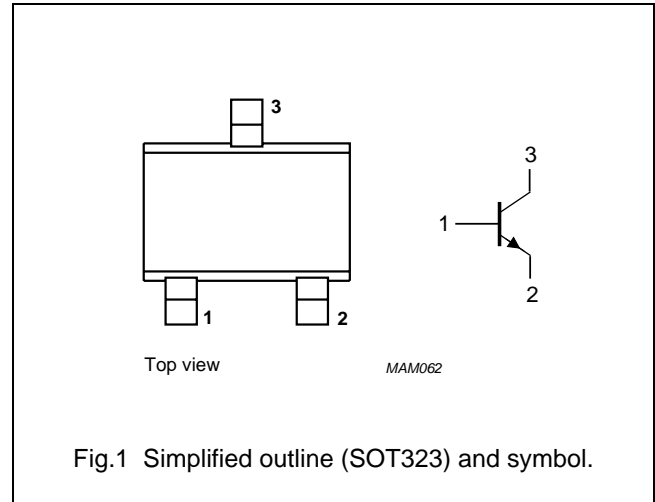
TYPE NUMBER	MARKING CODE ⁽¹⁾
PMST2222	*1B
PMST2222A	*1P

Note

- * = - : Made in Hong Kong.
* = t : Made in Malaysia.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter			
	PMST2222		–	60	V
	PMST2222A		–	75	V
V_{CEO}	collector-emitter voltage	open base			
	PMST2222		–	30	V
	PMST2222A		–	40	V
V_{EBO}	emitter-base voltage	open collector			
	PMST2222		–	5	V
	PMST2222A		–	6	V
I_C	collector current (DC)		–	600	mA
I_{CM}	peak collector current		–	800	mA
I_{BM}	peak base current		–	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$; note 1	–	200	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		–65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

NPN switching transistors

PMST2222; PMST2222A

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	625	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

$T_{amb} = 25\text{ °C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I_{CBO}	collector cut-off current PMST2222	$I_E = 0; V_{CB} = 50\text{ V}$	–	10	nA
		$I_E = 0; V_{CB} = 50\text{ V}; T_j = 125\text{ °C}$	–	10	μA
	collector cut-off current PMST2222A	$I_E = 0; V_{CB} = 60\text{ V}$	–	10	nA
		$I_E = 0; V_{CB} = 60\text{ V}; T_j = 125\text{ °C}$	–	10	μA
I_{EBO}	collector cut-off current	$I_C = 0; V_{EB} = 3\text{ V}$	–	10	nA
h_{FE}	DC current gain	$I_C = 0.1\text{ mA}; V_{CE} = 10\text{ V}$	35	–	
		$I_C = 1\text{ mA}; V_{CE} = 10\text{ V}$	50	–	
		$I_C = 10\text{ mA}; V_{CE} = 10\text{ V}$	75	–	
		$I_C = 10\text{ mA}; V_{CE} = 10\text{ V}; T_{amb} = -55\text{ °C}$	35	–	
		$I_C = 150\text{ mA}; V_{CE} = 1\text{ V}; \text{note 1}$	50	–	
		$I_C = 150\text{ mA}; V_{CE} = 10\text{ V}; \text{note 1}$	100	300	
	DC current gain PMST2222 PMST2222A	$I_C = 500\text{ mA}; V_{CE} = 10\text{ V}; \text{note 1}$	30 40	– –	
V_{CEsat}	collector-emitter saturation voltage PMST2222	$I_C = 150\text{ mA}; I_B = 15\text{ mA}; \text{note 1}$	–	400	mV
		$I_C = 500\text{ mA}; I_B = 50\text{ mA}; \text{note 1}$	–	1.6	V
	collector-emitter saturation voltage PMST2222A	$I_C = 150\text{ mA}; I_B = 15\text{ mA}; \text{note 1}$	–	300	mV
		$I_C = 500\text{ mA}; I_B = 50\text{ mA}; \text{note 1}$	–	1	V
V_{BEsat}	base-emitter saturation voltage PMST2222	$I_C = 150\text{ mA}; I_B = 15\text{ mA}; \text{note 1}$	–	1.3	V
		$I_C = 500\text{ mA}; I_B = 50\text{ mA}; \text{note 1}$	–	2.6	V
	base-emitter saturation voltage PMST2222A	$I_C = 150\text{ mA}; I_B = 15\text{ mA}; \text{note 1}$	0.6	1.2	V
		$I_C = 500\text{ mA}; I_B = 50\text{ mA}; \text{note 1}$	–	2	V
C_c	collector capacitance	$I_E = i_e = 0; V_{CB} = 10\text{ V}; f = 1\text{ MHz}$	–	8	pF
C_e	emitter capacitance PMST2222 PMST2222A	$I_C = i_c = 0; V_{EB} = 0.5\text{ V}; f = 1\text{ MHz}$	–	30	pF
			–	25	pF
f_T	transition frequency PMST2222 PMST2222A	$I_C = 20\text{ mA}; V_{CE} = 20\text{ V}; f = 100\text{ MHz}$	250	–	MHz
			300	–	MHz

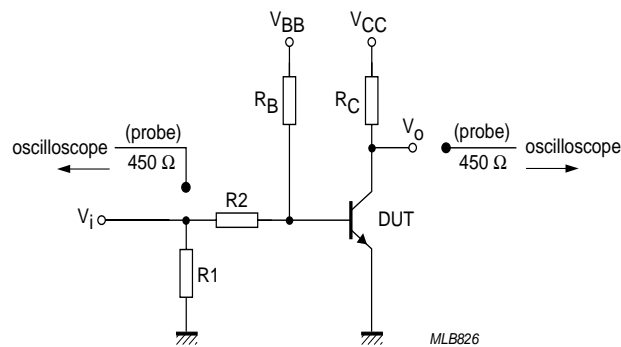
NPN switching transistors

PMST2222; PMST2222A

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
F	noise figure	$I_C = 200 \mu\text{A}$; $V_{CE} = 5 \text{ V}$; $R_S = 2 \text{ k}\Omega$; $f = 1 \text{ kHz}$; $B = 200 \text{ Hz}$	–	4	dB
Switching times (between 10% and 90% levels); (see Fig.2)					
t_{on}	turn-on time	$I_{Con} = 150 \text{ mA}$; $I_{Bon} = 15 \text{ mA}$; $I_{Boff} = -15 \text{ mA}$	–	35	ns
t_d	delay time		–	15	ns
t_r	rise time		–	20	ns
t_{off}	turn-off time		–	250	ns
t_s	storage time		–	200	ns
t_f	fall time		–	60	ns

Note

1. Pulse test: $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$.



$V_i = 9.5 \text{ V}$; $T = 500 \mu\text{s}$; $t_p = 10 \mu\text{s}$; $t_r = t_f \leq 3 \text{ ns}$.
 $R_1 = 68 \Omega$; $R_2 = 325 \Omega$; $R_B = 325 \Omega$; $R_C = 160 \Omega$.
 $V_{BB} = -3.5 \text{ V}$; $V_{CC} = 29.5 \text{ V}$.
 Oscilloscope input impedance $Z_i = 50 \Omega$.

Fig.2 Test circuit for switching times.

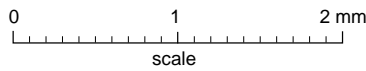
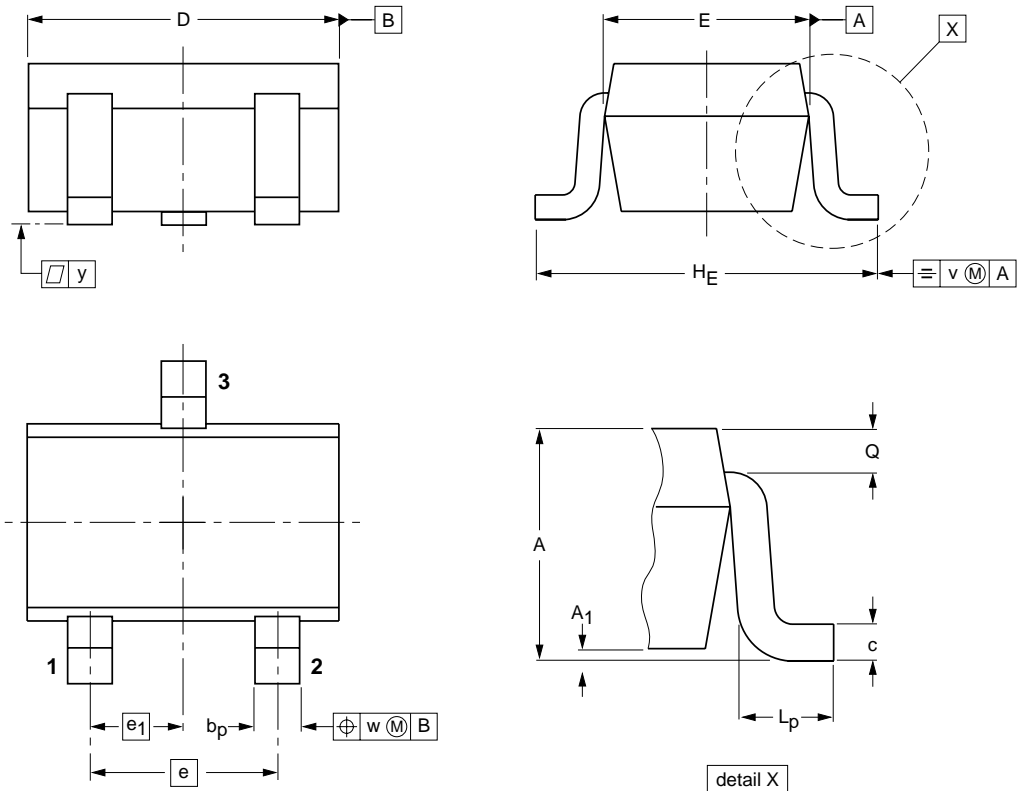
NPN switching transistors

PMST2222; PMST2222A

PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT323			SC-70		97-02-28

NPN switching transistors

PMST2222;
PMST2222A

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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